L Number	13:28 13:29 13:29
- 83473 bump US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISP TDB USPAT; USP TDB U	13:28 13:29 13:29
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US	13:29
- 83473 bump   IBM_TDB   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   USPAT; US-PGPUB; EPO; JPO; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT; USPAT;	13:29
- 83473 bump	13:29
- 1384 (438/106.ccls. or 438/108.ccls. or US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGP	13:29
- 1384 (438/106.ccls. or 438/108.ccls. or USPĀT; IBM TDB USPĀT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-	13:29
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	13:29
- 1384 (438/106.ccls. or 438/108.ccls. or 438/108.ccls. or 438/119.ccls.) and bump (USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPC; JPO; DERWENT; IBM_TDB USPAT; USP	13:29
- 1384 (438/106.ccls. or 438/108.ccls. or USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; US-PGPUB; US-PGPUB; US-PGPUB; US-P	13:29
438/119.ccls.) and bump  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO;	13:29
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB	
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO	
- 3285861 temperature	
- 3285861 temperature USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; DERWENT;	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;	
926 ((438/106.ccls. or 438/108.ccls. or 438/119.ccls.) and bump) and temperature US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;	13:30
- 926 ((438/106.ccls. or 438/108.ccls. or 438/119.ccls.) and bump) and temperature US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; IBM_TDB USPAT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;	13:30
- 926 ((438/106.ccls. or 438/108.ccls. or 438/108.ccls. or 438/119.ccls.) and bump) and temperature US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;	13:30
- 926 ((438/106.ccls. or 438/108.ccls. or 438/119.ccls.) and bump) and temperature USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;	13:30
438/119.ccls.) and bump) and temperature  US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	13:30
- 724029 bond EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	
T24029 bond DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; US-PGPUB; EP	
- 724029 bond IBM_TDB USPAT; 2004/08/11 US-PGPUB; EPO; JPO;	
- 724029 bond USPAT; 2004/08/11 US-PGPUB; EPO; JPO;	İ
US-PGPUB; EPO; JPO;	12.20
EPO; JPO;	13:30
IBM_TDB	13.31
US-PGPUB;	13.31
EPO; JPO;	
DERWENT;	
IBM TDB	i
- 63592 chip adj2 chip or flip\$4 adj2 chip USPAT; 2004/08/11	17:46
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM TDB	
- 723 (((438/106.ccls. or 438/108.ccls. or USPAT; 2004/08/11	17:34
438/119.ccls.) and bump) and temperature) US-PGPUB;	
and bond\$4 and (chip adj2 chip or flip\$4   EPO; JPO;	
adj2 chip) DERWENT;	
IBM_TDB	
- 304155 flux\$4 USPĀT; 2004/08/12	10:55
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM_TDB USDATE A 2004/09/11	17.42
- 4536311 bond\$4 or mount\$4 USPAT; 2004/08/11	11:43
US-PGPUB; EPO; JPO;	
DERWENT;	
IBM TDB	
- 102769 misalign\$5 or mis adj2 align\$5 USPAT; 2004/08/11	17.36
US-PGPUB;	1,.50
EPO; JPO;	
DERWENT;	
IBM TDB	
- 262642 melting adj2 point USPAT; 2004/08/12	11:00
US-PGPUB;	i
EPO; JPO;	
DERWENT;	ļ
IBM_TDB	
- 5625005 (bond\$4 or mount\$4) or assembl\$4 USPAT; 2004/08/12	10 1
US-PGPUB;	IU:54
EPO; JPO;	10:54
DERWENT;	10:54
IBM TDB	10:54

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	71402		IIODAM.	10004/00/11 17-40
-	71483	temperature near5 (melting adj2 point)	USPAT; US-PGPUB;	2004/08/11 17:42
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	9969		USPAT;	2004/08/11 17:42
		same (chip or die or substrate or wafer)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	6252	(bond\$4 or mount\$4) and ((temperature	USPAT:	2004/08/11 17:45
-		near5 (melting adj2 point)) same (chip or	US-PGPUB;	
		die or substrate or wafer))	EPO; JPO;	
			DERWENT;	
	17552	huma acous (handed au maurated)	IBM_TDB	2004/08/11 17:45
-	17553	bump near5 (bond\$4 or mount\$4)	USPAT; US-PGPUB;	2004/08/11 17:45
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	411		USPAT;	2004/08/11 17:45
		near5 (melting adj2 point)) same (chip or	US-PGPUB;	
		die or substrate or wafer))) and (bump near5 (bond\$4 or mount\$4))	EPO; JPO; DERWENT;	
		nears (bonds4 or mounts4))	IBM TDB	
_	314	(((bond\$4 or mount\$4) and ((temperature	USPAT;	2004/08/11 17:46
		near5 (melting adj2 point)) same (chip or	US-PGPUB;	
		die or substrate or wafer))) and (bump	EPO; JPO;	
		near5 (bond\$4 or mount\$4))) and (chip adj2	DERWENT;	
	18300	chip or flip\$4 adj2 chip)	IBM_TDB USPAT;	2004/08/12 10:52
-	18300	temporar\$4 near4 fix\$4	US-PGPUB;	2004/06/12 10:32
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	589481	1 '	USPAT;	2004/08/12 10:53
		chip or substrate)	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
1 -	527		USPĀT;	2004/08/12 10:53
1		chip or substrate) adj6 (bump or chip or	US-PGPUB;	
		substrate))	EPO; JPO; DERWENT;	
			IBM TDB	
_	5627850	(bond\$4 or mount\$4) or assembl\$4	USPAT;	2004/08/12 10:54
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	424	((temporar\$4 near4 fix\$4) same ((bump or	IBM_TDB USPAT;	2004/08/12 10:54
	"2"	chip or substrate) adj6 (bump or chip or	US-PGPUB;	=====================================
		substrate))) and ((bond\$4 or mount\$4) or	EPO; JPO;	
		assembl\$4 )	DERWENT;	
	12226	6164 page 15 (b page 15 page	IBM_TDB	2004/09/12 10:50
-	13336	flux\$4 near15 (bump or chip or substrate)	USPAT; US-PGPUB;	2004/08/12 10:56
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	42	1 1 1 1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	USPAT;	2004/08/12 10:56
		chip or substrate) adj6 (bump or chip or substrate))) and ((bond\$4 or mount\$4) or	US-PGPUB; EPO; JPO;	
		assembl\$4 )) and ((bond\$4 or mount\$4) or assembl\$4 )) and (flux\$4 near15 (bump or	DERWENT;	
		chip or substrate))	IBM TDB	
-	263226		USPAT;	2004/08/12 11:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
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-	16	((((temporar\$4 near4 fix\$4) same ((bump or	USPAT;	2004/08/12 11:01
		chip or substrate) adj6 (bump or chip or	US-PGPUB;	
		substrate))) and ((bond\$4 or mount\$4) or	EPO; JPO;	
		assembl\$4 )) and (flux\$4 near15 (bump or	DERWENT;	
		chip or substrate))) and (melting adj3	IBM_TDB	
		point )	_	